Title (en)

POTTED ELECTRICAL/MECHANICAL DEVICES, AND DUAL CURE POTTING METHOD

Publication

EP 0313574 B1 19930324 (EN)

Application

EP 87904775 A 19870702

Priority

US 88267086 A 19860707

Abstract (en)

[origin: WO8800135A1] A device, e.g., an electrical or electromechanical assembly (62), comprising a housing (64) with a mechanism (66) disposed therein which is potted by a cured mass of self-leveling liquid composition. The composition comprises an actinic radiation cured first resin component (102) preferably (meth)acrylate resins, which immobilize the partially cured mass, and a subsequently cured second resin component (100), preferably epoxy resins, which is non-cured under the actinic radiation but curable at ambient or elevated temperature. Depending on the depth of the composition which is to be cured in the housing, it may be desirable to utilize the self-leveling liquid composition as either a single homogeneous mixture of the first and second resin components, or, where the depth of the housing is greater than the depth of UV penetration, as cured mass wherein the first resin component is in a separate and discrete resin layer overlying a lower resin layer containing the second resin component but not the first resin component.

IPC 1-7

B32B 27/16; G01F 15/14; H01C 1/028; H01C 1/032; H01C 1/034; H01C 1/036; H05K 7/12

IPC 8 full level

H05K 3/28 (2006.01); **B29C 33/06** (2006.01); **B29C 35/02** (2006.01); **B29C 35/08** (2006.01); **B29C 39/10** (2006.01); **B29C 70/72** (2006.01); **B32B 27/16** (2006.01); **C08G 18/04** (2006.01); **C08G 18/40** (2006.01); **C08G 18/42** (2006.01); **C08G 59/00** (2006.01); **C08G 59/40** (2006.01); **C08L 63/00** (2006.01); **G01F 15/00** (2006.01); **G01F 15/14** (2006.01); **H01B 3/30** (2006.01); **H01B 3/40** (2006.01); **H01B 3/44** (2006.01); **H01C 1/024** (2006.01); **H01C 1/028** (2006.01); **H01C 1/032** (2006.01); **H01C 1/034** (2006.01); **H01C 1/036** (2006.01); **H01C 10/32** (2006.01); **H01F 27/00** (2006.01); **H01G 4/224** (2006.01); **H01H 11/00** (2006.01); **H05K 5/00** (2006.01); **H05K 7/12** (2006.01); B29K 105/22 (2006.01); B29L 31/34 (2006.01)

IPC 8 main group level

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CPC (source: EP)

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